



제 31회 한국반도체학술대회

The 31st Korean Conference on Semiconductors

2024년 1월 24일(수)-26일(금) | 경주화백컨벤션센터(HICO)

2024년 1월 25일(목), 10:55-12:40

Room A(101), 1층

B. Patterning (Lithography & Etch Technology) 분과

[TA2-B] Advanced Plasma Etching I

좌장: 유신재 교수(충남대학교)

<p>초청발표 TA2-B-1 10:55-11:30</p>	<p>TCAD Augmented Generative Adversarial Network for Optimizing a Chip Level Size Mask-layout Design in HARC Etching Process Hyoungcheol Kwon¹, Hyunsuk Huh², Hwiwon Seo¹, Songhee Han¹, Imhee Won¹, Dongyeon Oh¹, Felipe Iza³, Seungchul Lee², Sung Kye Park¹, and Seonyong Cha⁴ ¹Design Input Center, SK hynix, ²Department of Mechanical Engineering, POSTECH, ³The Wolfson School of Mechanical, Electrical and Manufacturing Engineering, Loughborough University, ⁴R&D Devision, SK hynix</p>
<p>TA2-B-2 11:30-11:45</p>	<p>Contact-hole Reduction Using Advanced Cyclic Etching Process in Heptafluoropropyl Methyl Ether Plasmas 유상현^{1,2}, 김창구^{1,2} ¹Department of Chemical Engineering, Ajou University, ²Department of Energy Systems Research, Ajou University</p>
<p>TA2-B-3 11:45-12:00</p>	<p>Investigation of Etching Profile Transition in SiO₂ Etching Using Ar/CF₄ Discharges 정원녕¹, 최병엽¹, 김시준², 이영석², 성인호¹, 조철희¹, 최민수¹, 설유빈², 이우빈¹, 서성현¹, 유신재^{1,2} ¹Department of Physics, Chungnam National University, ²IQS, Chungnam National University</p>
<p>초청발표 TA2-B-4 12:00-12:30</p>	<p>Plasma-Enhanced Atomic Layer Etching for Metals and Dielectric Materials Heeyeop Chae School of Chemical Engineering, Sungkyunkwan University</p>
<p>TA2-B-5 12:30-12:45</p>	<p>Plasma Atomic Layer Etching of Titanium Nitride with Surface Fluorination or Chlorination Heeju Ha¹, Hyeongwu Lee², Minsung Jeon³, and Heeyeop Chae^{1,2,3} ¹School of Chemical Engineering, Sungkyunkwan University, ²Department of Nano Science and Technology, SKKU Advanced Institute of Nanotechnology (SAINT), Sungkyunkwan University, ³Department of Semiconductor Convergence Engineering, Sungkyunkwan University</p>